Ming Kong

List of Publications by Year in descending order

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1163117 1281871 12 187 8 11 citations h-index g-index papers 12 12 12 145 all docs docs citations times ranked citing authors

#	Article	IF	CITATIONS
1	Investigations on the microstructure and hardening mechanism of TiN/Si3N4nanocomposite coatings. Journal Physics D: Applied Physics, 2007, 40, 2858-2863.	2.8	54
2	Template-induced crystallization of amorphous SiO2 and its effects on the mechanical properties of TiNâ •SiO2 nanomultilayers. Applied Physics Letters, 2005, 86, 021919.	3.3	39
3	Crystallization of amorphous SiC and superhardness effect in TiN/SiC nanomultilayers. Applied Surface Science, 2007, 253, 4734-4739.	6.1	27
4	Growth, microstructure and mechanical properties of (Ti, Al)N/VN nanomultilayers. Materials Letters, 2006, 60, 874-877.	2.6	12
5	Epitaxial growth and superhardness effect of TiN/AlON nanomultilayers synthesized by reactive magnetron sputtering technology. Journal of Alloys and Compounds, 2009, 485, 435-438.	5.5	11
6	Research Development of Hard Ceramic Nano-multilayer Films. Wuji Cailiao Xuebao/Journal of Inorganic Materials, 2010, 25, 113-119.	1.3	11
7	Microstructure, mechanical properties, and high-temperature oxidation resistance of AlN/SiO2 nanomultilayer coatings. Journal of Coatings Technology Research, 2012, 9, 177-182.	2.5	10
8	Crystallization of Al2O3 and its effects on the mechanical properties in TiNâ^•Al2O3 nanomultilayers. Journal of Applied Physics, 2005, 98, 074302.	2.5	8
9	Pseudocrystallization of SiO2 and superhardness effects of AlNâ [*] -SiO2 nanomultilayers. Journal of Applied Physics, 2008, 103, 043506.	2.5	6
10	Development and Experimental Validation of a 3-D Solder Self-Alignment Model for Alignment Accuracy Prediction of Flip-Chip Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1523-1532.	2.5	6
11	Influences of Solder Wetting on Self-Alignment Accuracy and Modeling for Optoelectronic Devices Assembly. Journal of Electronic Packaging, Transactions of the ASME, 2012, 134, .	1.8	3
12	Effects of Solder Wetting on Self-Alignment Accuracy and Modeling for Optoelectronics Assembly. , 2010, , .		0